Compliant with IEC 62474/ D9.00 Compliant to IEC 61249-2-21:2003

MICROCHIP			Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)				J-STD-609A Product Marking and/or Pkg. Labeling
Semiconductor Device Type:	(DAA)	004 SOT-143 NiPdAu								e4
Basic Substance	CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm	5.57	(mg) Total	Mold Compound	% ot Total Weight	50.63
Silica, vitreous	60676-86-0	Mold Compound	43.036	4.734	430,355		Silica, vitreous	60676-86-0	85.00	
Epoxy Resin	Trade Secret	Mold Compound	3.101	0.341	31,011	1	Epoxy Resin	Trade Secret	6.13	
Phenolic Resin	Trade Secret	Mold Compound	3.101	0.341	31,011		Phenolic Resin	Trade Secret	6.13	
Epoxy, Cresol Novolac	29690-82-2	Mold Compound	1.240	0.136	12,404		Epoxy, Cresol Novolac	29690-82-2	2.45	
Carbon Black	1333-86-4	Mold Compound	0.152	0.017	1,519		Carbon Black	1333-86-4	0.30	
Copper	7440-50-8	Lead Frame	42.666	4.693	426,661			Total	100.00	
Iron	7439-89-6	Lead Frame	1.009	0.111	10,086	4.82	(mg) Total	Lead Frame	% of Total Weight	43.85
Phosphorous	7723-14-0	Lead Frame	0.110	0.012	1,096		Copper	7440-50-8	97.30	
Zinc (Metal)	7440-66-6	Lead Frame	0.066	0.007	658	1	Iron	7439-89-6	2.30	
Silver (Ag)	7440-22-4	Die Attach	0.997	0.110	9,970	1	Phosphorous	7723-14-0	0.25	
Proprietary Resin	Trade Secret	Die Attach	0.235	0.026	2,350	1	Zinc (Metal)	7440-66-6	0.15	
Proprietary Curing agent & Hardener	Trade Secret	Die Attach	0.038	0.004	381	1		Total	100.00	ļi.
Silicon	7440-21-3	Chip (Die)	2.360	0.260	23.600	0.14	(mg) Total	Die Attach	% of Total Weight	1.27
Gold	7440-57-5	Wire Bond	0.926	0.102	9.260	84-1LMISR4	Silver (Ag)	7440-22-4	78.50	1.27
Nickel	7440-02-0	Plating on external leads (pins)	0.864	0.095	8,640	- 12.11.1014	Proprietary Resin	Trade Secret	18.50	
Palladium	7440-05-3	Plating on external leads (pins)	0.048	0.005	480	Pror	prietary Curing agent & Han	Trade Secret	3.00	
	7440-03-3	riating on external leads (pins)	0.040			FIUL	nietary Curing agent & Han			
	7110 57 5	Disting an external leads (pins)	0.040	0.005						
Gold	7440-57-5	Plating on external leads (pins)	0.048	0.005	480			Total	100.00	
		TOTALS:	0.048 99.996	0.005 11.000	999,960	0.26	Total (mg)	Chip (Die)	% of Total Weight	2.36
Gold semiconductor device and its homogenous ma 363/EU (31 March 2015) and 2002/53/EC (End-	0.0110 aterials comply w	TOTALS: g Total Mass ith EU Directives: 2002/95/EC (27 January 2003) 8 ELV) without exemption (zero)	99.996 & Directive 201	11.000 1/65/EU (08 Ju	999,960		Doped Silicon	Chip (Die) 7440-21-3 Total	% of Total Weight 100.00 100.00	
Gold semiconductor device and its homogenous ma 363/EU (31 March 2015) and 2002/53/EC (End-	0.0110 aterials comply w	TOTALS: g Total Mass ith EU Directives: 2002/95/EC (27 January 2003) 8	99.996 & Directive 201	11.000 1/65/EU (08 Ju	999,960	0.26		Chip (Die) 7440-21-3	% of Total Weight 100.00	0.93
Gold semiconductor device and its homogenous mages/EU (31 March 2015) and 2002/53/EC (Endi- liance with the above EU Directives has been semical substance is absent from the list above chip Technology Incorporated's knowledge ar	0.0110 aterials comply w of-Life Vehicles (i verified via interi e, the chemical s and belief as of the	TOTALS: g Total Mass ith EU Directives: 2002/95/EC (27 January 2003) 8 ELV) without exemption (zero)	99.996 3 Directive 201 analytical test of the emiconductor on the believe that	11.000 1/65/EU (08 Judata. device and, to the unavoida	999,960 ine 2011) and the best of		Doped Silicon	Chip (Die) 7440-21-3 Total	% of Total Weight 100.00 100.00	
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